

ABSTRACT OF THE DISCLOSURE

5 A substrate and method of encapsulating a
substrate based electronic package using injection molding
and a two piece mold is described. The substrate has a
barrier material formed on a gating region of the substrate.
The barrier material can be formed directly over circuit
wiring traces formed on the substrate thereby avoiding
restrictions on the location of circuit wiring traces. The
barrier material and encapsulant are chosen such that the
adhesive force between the barrier material and the
encapsulant is greater than the adhesive force between the
barrier material and the substrate. When the mold runner is
broken away the barrier material is also peeled away without
damage to the substrate or circuit wiring traces.